GONDA
光达科技

明星产品
Flagship products

PERC背银浆料
PERC Back-Side Silver Paste

GB21/GB22系列
GB21/GB22 Series

适用范围 Application

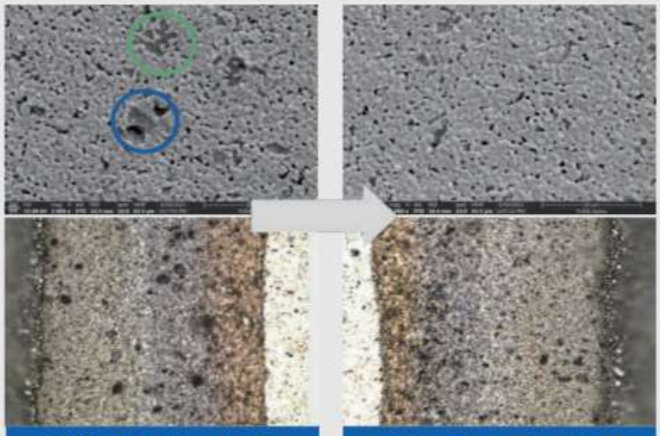
- 适用于PERC电池技术路线
  Applicable for PERC solar cell technology routes.

亮点 Highlights

- 更宽的烧结窗口（720-790℃）
  Wider firing window (720-790°C).
- 优异的拉力和老化拉力，焊接窗口宽
  Excellent initial pull strength and aged pull strength, with a wide soldering window.
- 超低单耗，低串阻、钝化层破坏少，杂质复合低
  Ultra-low specific paste consumption, low series resistance (Rs), minimal damage to the passivation layer, and low impurity recombination.
- 适合多种工艺，单面、双面、MBB等
  Compatible with multiple process designs, including single-sided, double-sided, and MBB (Multi-Busbar).
- 兼容166-210尺寸电池高速印刷
  Compatible with high-speed printing on 166-210mm solar cells.

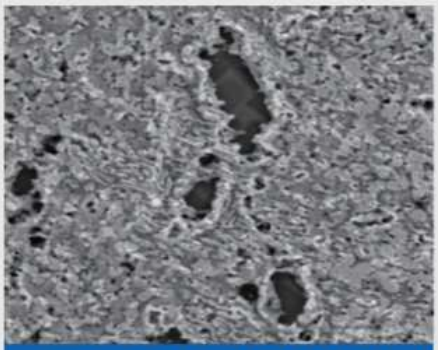
检测类型 Test Parameter	检测方法 Test Method	控制范围 Control Range	单位 Unit
粘度 Viscosity	Bookfiled HB-DV2T, 52#转子@10RPM,25±0.1℃	15-70	pa·S
细度 Fineness	刮板细度计-2th Scraper Fineness Gauge - 2 passes	≤12	μm
固含量 Solid Content		55-69	wt,%

背银开发方向：提高银层致密性，改善电阻
Back-Side Silver Development Direction: Enhance Silver Layer Density.



搭接区孔洞明显漏硅
Obvious Si (Silicon) leakage/ exposure at contact area holes.

搭接区孔洞无明显漏硅
No obvious Si (Silicon) leakage/ exposureat contact area holes.



银铝搭接区孔洞部分SEM图片
SEM image of the hole areas in the Ag-Al contact region.